

EXPRESS MAIL NO.: ER 843 143 706 US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of: CHEAH, et. al.

Confirmation No.: 9901

Application No.: 10/068,523

Art Unit: 2826

Filed: February 5, 2002

Examiner: Alexander O. Williams

For: *THERMALLY ENHANCED METAL  
CAPPED BGA PACKAGE*

Attorney Docket No.: 060889-0066  
(formerly 9818-066-999)

**ISSUE FEE TRANSMITTAL COVER LETTER**

**BOX ISSUE FEE**

**Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22323-1450**

Dear Sir/Madam:

Enclosed please find Form PTOL-85 and a copy thereof authorizing payment of the issue fee for the above-identified application. Please charge the issue fee, estimated to be \$1,400, and any additional fees that may be required, to Morgan, Lewis & Bockius LLP Deposit Account No. 50-0310. A copy of this letter is enclosed.

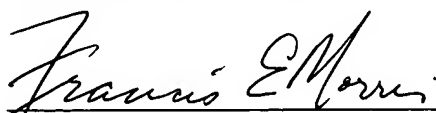
Also enclosed please find a completed form for Change of Correspondence Address requesting that all correspondence be addressed to:

Morgan, Lewis & Bockius LLP  
1111 Pennsylvania Avenue  
Washington, D.C. 20004

A request was previously made in October, 2004 to change the correspondence address to the address given above when a customer number 48591 was established with this address and a form was submitted requesting that the serial number of the present application and that of many other applications be associated with this customer number.

Date March 9, 2005

Respectfully submitted,

  
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